



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Fee et al.

Serial No.: 10/729,180

Filed: December 5, 2003

For: QUAD FLAT NO LEAD (QFN) GRID
ARRAY PACKAGE, METHOD OF
MAKING AND MEMORY MODULE AND
COMPUTER SYSTEM INCLUDING SAME

Confirmation No.: 8592

Examiner: T. Le

Group Art Unit: 2827

Attorney Docket No.: 2269-4738.2US
(00-1113.02/US)

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COMMENTS ON STATEMENT OF REASONS FOR ALLOWANCE

Mail Stop Issue Fee
Commissioner for Patents
PO Box 1450
Alexandria, VA 22313-1450

Sir:

Prior to the issuance of the Notice of Allowability, the Examiner stated that:

Claims 1-13 include allowable subject matter since the prior art made of record and considered pertinent to the applicant's disclosure does not teach or suggest the claimed limitations. Casper (U.S. Patent No. 6,184,067), Casper (U.S. Patent No. 6,587,892, and others, does not teach the claimed invention having a recess in the dielectric encapsulant between at least one conductive element of the at least a first set of conductive elements and at least one adjacent conductive element of the at least one other set of conductive elements.

And further stated:

Claims 1-6, 11-20 include allowable subject matter since the prior art made of record and considered pertinent to the applicant's disclosure does not teach or suggest the claimed limitations. Keown et al. (U.S. Patent No. 5,286,656), and others, does not teach the claimed invention having a dielectric encapsulant formed over the semiconductor die and defining the outer lateral periphery of the integrated circuit package, the dielectric encapsulant extending at least partially laterally about the plurality of conductive elements and leaving an outer surface of each conductive element exposed; and a recess in the dielectric encapsulant between at least one conductive element of the at least a first set of conductive elements and at least one adjacent conductive element of the at least one other set of conductive elements.

Applicants note that the independent claims as allowed include other and different language than that particularly cited by the Examiner, and the allowed dependent claims include other and further features and elements. Accordingly, the scope of the claims must be determined from the literal language of each as a whole, as well as equivalents thereof.

Respectfully submitted,



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